

# 8-Input Data Selector/Multiplexer

## MC74HC151A

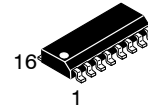
The MC74HC151A is identical in pinout to the LS151. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device selects one of the eight binary Data Inputs, as determined by the Address Inputs. The Strobe pin must be at a low level for the selected data to appear at the outputs. If Strobe is high, the Y output is forced to a low level and the  $\bar{Y}$  output is forced to a high level.

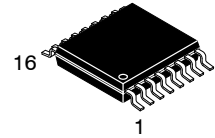
The HC151A is similar in function to the HC251 which has 3-state outputs.

### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 328 FETs or 82 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



SOIC-16  
D SUFFIX  
CASE 751B

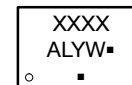
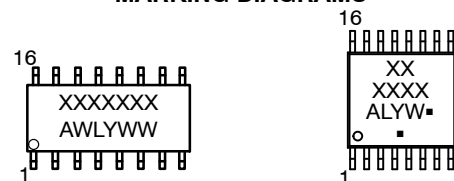


TSSOP-16  
DT SUFFIX  
CASE 948F



QFN16  
MN SUFFIX  
CASE 485AW

### MARKING DIAGRAMS



- |        |                     |
|--------|---------------------|
| A      | = Assembly Location |
| WL, L  | = Wafer Lot         |
| YY, Y  | = Year              |
| WW, W  | = Work Week         |
| G or ■ | = Pb-Free Package   |
- (Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

MC74HC151A

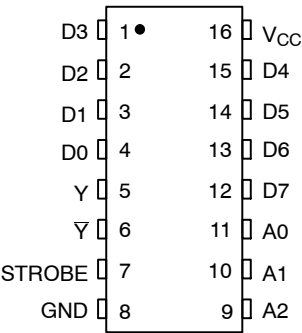


Figure 1. Pin Assignment

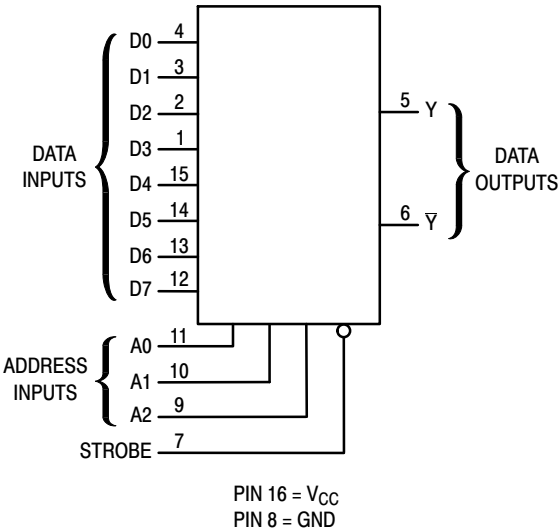


Figure 2. Logic Diagram

FUNCTION TABLE

Inputs				Outputs	
A2	A1	A0	Strobe	Y	$\bar{Y}$
X	X	X	H	L	H
L	L	L	L	D0	$\bar{D0}$
L	L	H	L	D1	$\bar{D1}$
L	H	L	L	D2	$\bar{D2}$
L	H	H	L	D3	$\bar{D3}$
H	L	L	L	D4	$\bar{D4}$
H	L	H	L	D5	$\bar{D5}$
H	H	L	L	D6	$\bar{D6}$
H	H	H	L	D7	$\bar{D7}$

D0, D1, ..., D7 = the level of the respective D input.

# MC74HC151A

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	DC Supply Voltage	−0.5 to +6.5	V	
V <sub>IN</sub>	DC Input Voltage	−0.5 to V <sub>CC</sub> + 0.5	V	
V <sub>OUT</sub>	DC Output Voltage	−0.5 to V <sub>CC</sub> + 0.5	V	
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA	
I <sub>OUT</sub>	DC Output Current, per Pin	±25	mA	
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA	
I <sub>IK</sub>	Input Clamp Current (V <sub>IN</sub> < 0 or V <sub>IN</sub> > V <sub>CC</sub> )	±20	mA	
I <sub>OK</sub>	Output Clamp Current (V <sub>OUT</sub> < 0 or V <sub>OUT</sub> > V <sub>CC</sub> )	±20	mA	
T <sub>STG</sub>	Storage Temperature	−65 to +150	°C	
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C	
T <sub>J</sub>	Junction Temperature Under Bias	±150	°C	
θ <sub>JA</sub>	Thermal Resistance (Note 1)	SOIC−16 QFN16 TSSOP−16	126 118 159	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 25°C	SOIC−16 QFN16 TSSOP−16	995 1062 787	mW
MSL	Moisture Sensitivity	Level 1	–	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	–
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage	2.0	6.0	V	
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Note 3)	0	V <sub>CC</sub>	V	
T <sub>A</sub>	Operating Free-Air Temperature	−55	+125	°C	
t <sub>r</sub> , t <sub>f</sub>	Input Rise or Fall Time	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	0 0 0	1000 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

3. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

# MC74HC151A

## DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				-55 to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>					V
		I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	
		I <sub>OUT</sub>   ≤ 2.4 mA  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.2 3.7 5.2	
V <sub>OL</sub>	Minimum Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>					V
		I <sub>OUT</sub>   ≤ 20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	
		I <sub>OUT</sub>   ≤ 2.4 mA  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.4 0.4 0.4	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	8.0	80	160	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# MC74HC151A

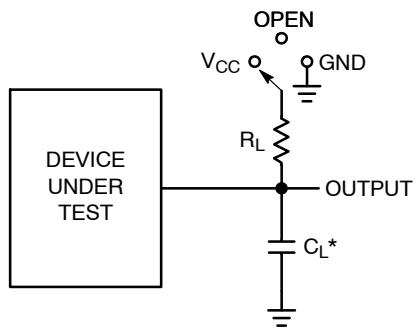
## AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			-55 to 25°C	≤ 85°C	≤ 125°C	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, D to Y (Figures 3 and 4)	2.0	170	215	255	ns
		3.0	TBD	TBD	TBD	
		4.5	34	43	51	
		6.0	29	37	43	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, D to $\bar{Y}$ (Figures 3 and 4)	2.0	185	230	280	ns
		3.0	TBD	TBD	TBD	
		4.5	37	46	56	
		6.0	31	39	48	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, A to Y (Figures 3 and 4)	2.0	185	230	280	ns
		3.0	TBD	TBD	TBD	
		4.5	37	46	56	
		6.0	31	39	48	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, A to $\bar{Y}$ (Figures 3 and 4)	2.0	205	255	310	ns
		3.0	TBD	TBD	TBD	
		4.5	41	51	62	
		6.0	35	43	53	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, STROBE to Y or $\bar{Y}$ (Figures 3 and 4)	2.0	125	155	190	ns
		3.0	TBD	TBD	TBD	
		4.5	25	31	38	
		6.0	21	26	32	
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 3 and 4)	2.0	75	95	110	ns
		3.0	30	40	55	
		4.5	15	19	22	
		6.0	13	16	19	
C <sub>IN</sub>	Maximum Input Capacitance	–	10	10	10	pF

C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output) (Note 4)	5.0	Typical @ 25°C	pF
			36	

4. Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} \times V_{CC}^2 \times f + I_{CC} \times V_{CC}$ .

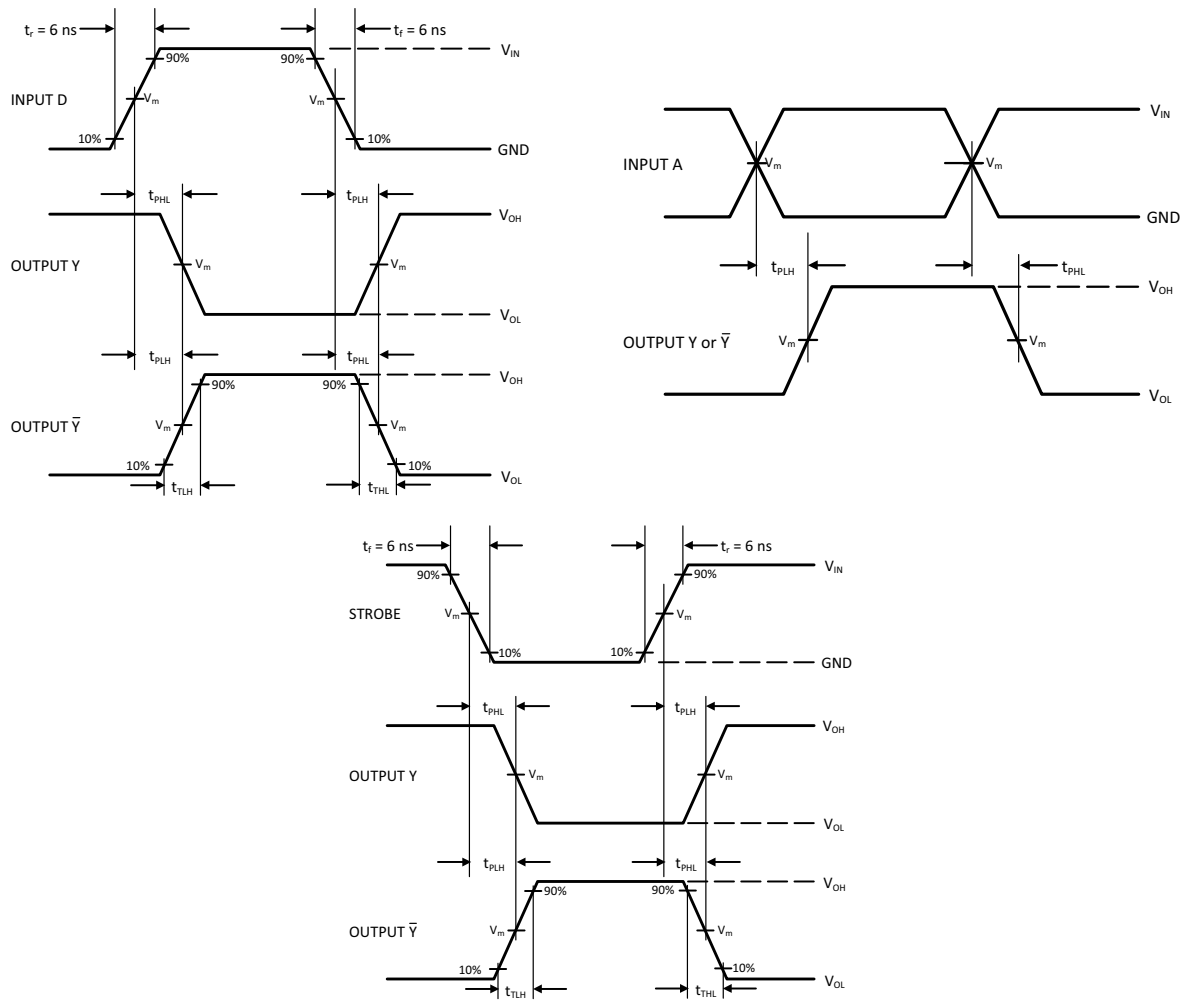
# MC74HC151A



\*C<sub>L</sub> Includes probe and jig capacitance

Test	Switch Position	C <sub>L</sub>	R <sub>L</sub>
t <sub>PLH</sub> / t <sub>PHL</sub>	Open	50 pF	1 kΩ
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>CC</sub>		
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND		

Figure 3. Test Circuit



Device	V <sub>IN</sub> , V	V <sub>m</sub> , V
MC74HC151A	V <sub>CC</sub>	50% x V <sub>CC</sub>

Figure 4. Switching Waveforms

## MC74HC151A

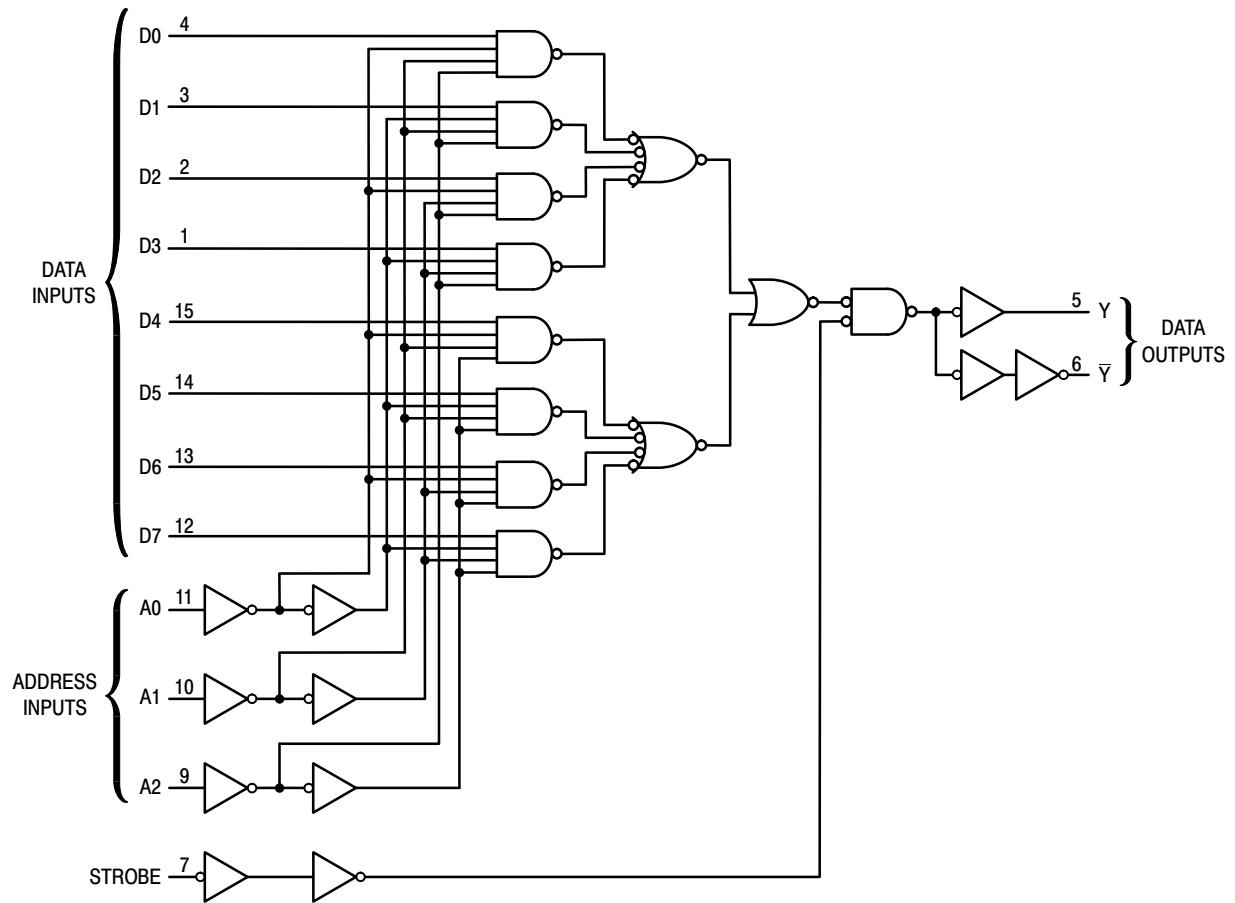


Figure 5. Expanded Logic Diagram

### PIN DESCRIPTIONS

#### INPUTS

##### **D0, D1, ... , D7 (Pins 4, 3, 2, 1, 15, 14, 13, 12)**

Data inputs. Data on any one of these eight binary inputs may be selected to appear on the output.

#### CONTROL INPUTS

##### **A0, A1, A2 (Pins 11, 10, 9)**

Address inputs. The data on these pins are the binary address of the selected input (see the Function Table).

##### **Strobe (Pin 7)**

Strobe. This input pin must be at a low level for the selected data to appear at the outputs. If the Strobe pin is high, the Y output is forced to a low level and the  $\bar{Y}$  output is forced to a high level.

#### OUTPUTS

##### **Y, $\bar{Y}$ (Pins 5, 6)**

Data outputs. The selected data is presented at these pins in both true (Y output) and complemented ( $\bar{Y}$  output) forms.

## MC74HC151A

### ORDERING INFORMATION

Device	Package	Marking	Shipping†
MC74HC151ADR2G	SOIC-16	HC151AG	1000 / Tape & Reel
MC74HC151ADR2G-Q*	SOIC-16	HC151AG	1000 / Tape & Reel
MC74HC151ADTG	TSSOP-16	HC 151A	75 Units / Rail
MC74HC151ADTR2G	TSSOP-16	HC 151A	2500 / Tape & Reel
MC74HC151ADTR2G-Q*	TSSOP-16	HC 151A	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



# MC74HC151A

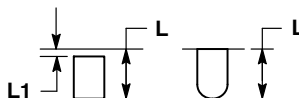
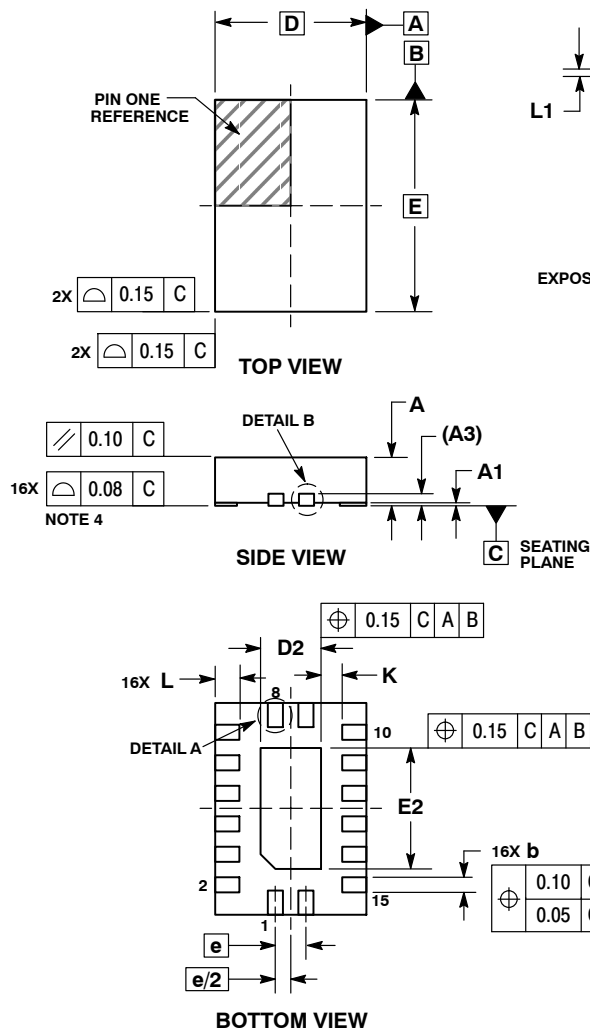
## PACKAGE DIMENSIONS



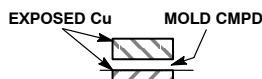
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QFN16, 2.5x3.5, 0.5P  
CASE 485AW  
ISSUE O

DATE 11 DEC 2008



**DETAIL A**  
ALTERNATE TERMINAL  
CONSTRUCTIONS



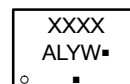
**DETAIL B**  
ALTERNATE  
CONSTRUCTIONS

### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.50	BSC
D2	0.85	1.15
E	3.50	BSC
E2	1.85	2.15
e	0.50	BSC
K	0.20	---
L	0.35	0.45
L1	---	0.15

### GENERIC MARKING DIAGRAM\*

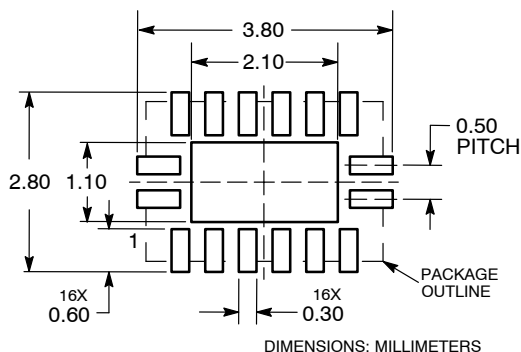


- XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

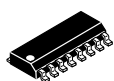
### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS



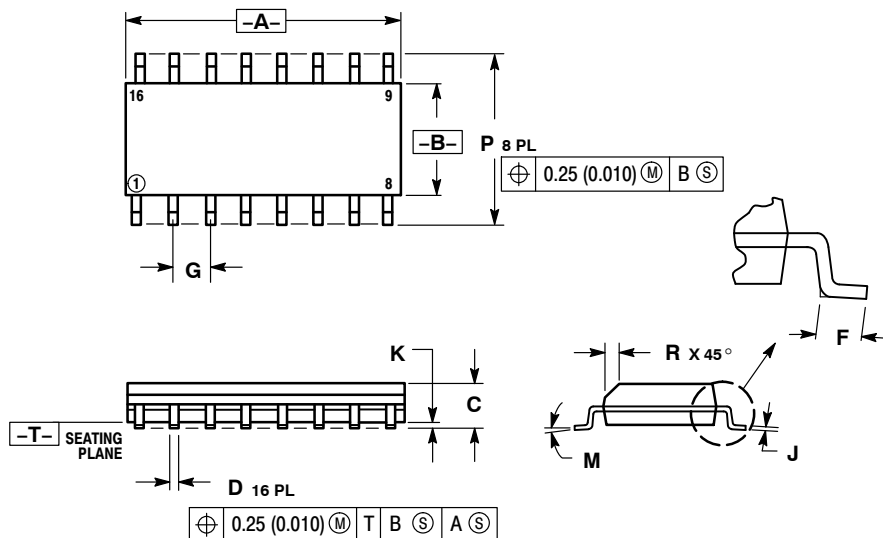
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### SOIC-16

#### CASE 751B-05

#### ISSUE K

DATE 29 DEC 2006



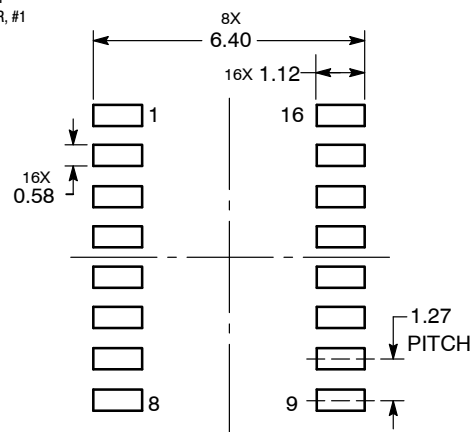
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1: PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR	STYLE 2: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE	STYLE 3: PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4	STYLE 4: PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1
STYLE 5: PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE	STYLE 7: PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH	

#### RECOMMENDED SOLDERING FOOTPRINT\*



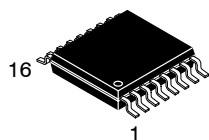
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOIC-16	PAGE 1 OF 1

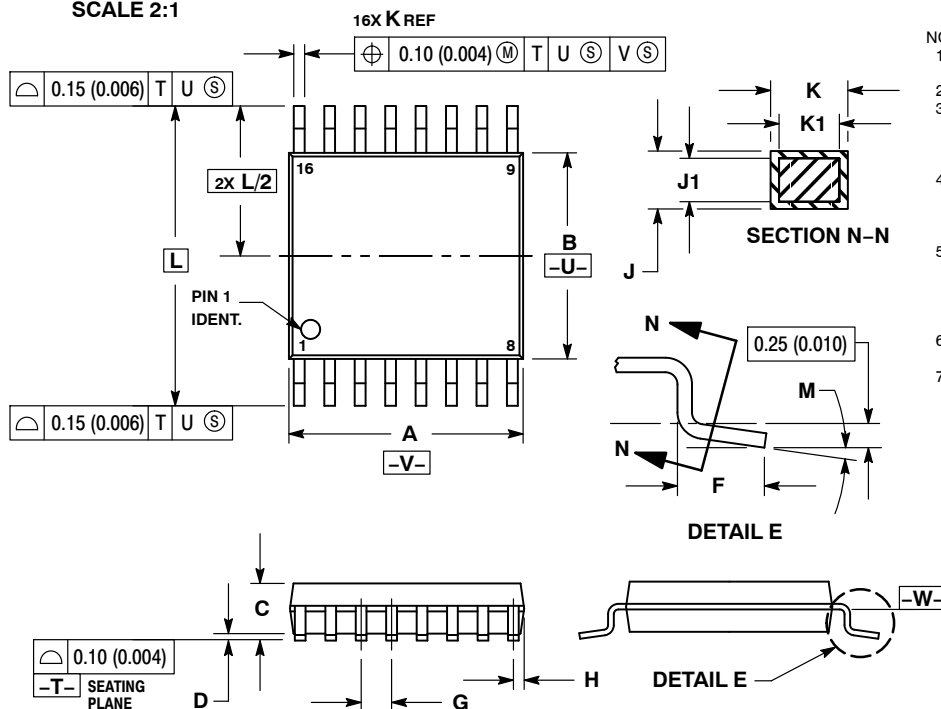
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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**TSSOP-16 WB**  
**CASE 948F**  
**ISSUE B**

DATE 19 OCT 2006

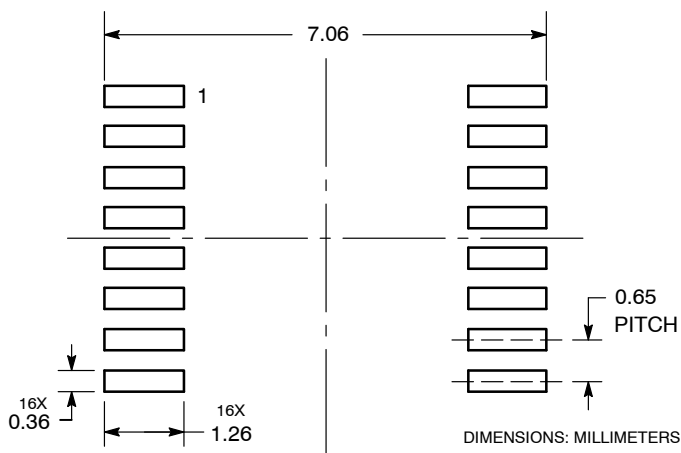


## NOTES:

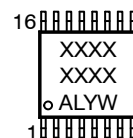
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

## RECOMMENDED SOLDERING FOOTPRINT\*



## GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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